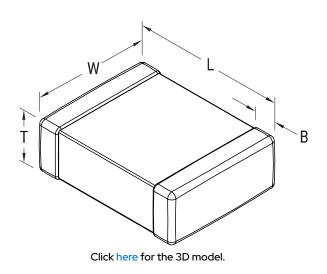




CBR-SMD RF COG, Ceramic, 24 pF, 2%, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
Т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

VV	0.611111 +/-0.111111	voltage DC	30 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	125 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.114%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hou
Packaging Quantity	4000	Insulation Resistance	10 GOhms

**Specifications** 

Capacitance	24 pF
Tolerance	2%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.114%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	880

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